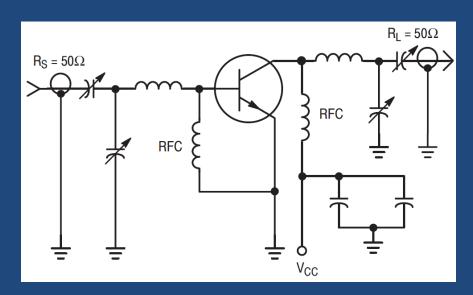
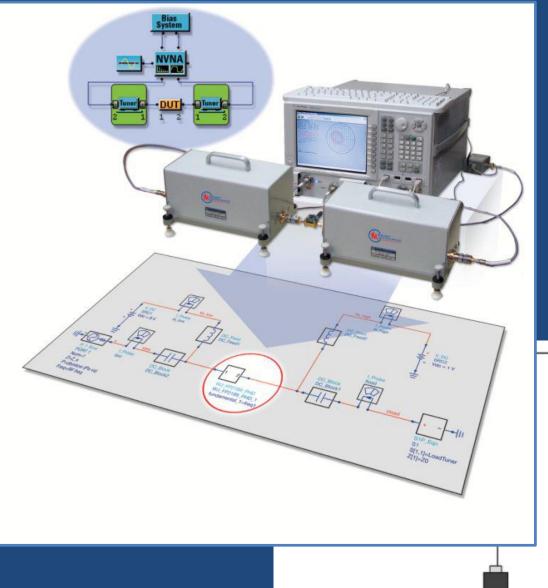
AP de RF – Load Pull: Portada 1

Amplificadores de Potencia de RF Load Pull

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Año 2016

- Load Pull definición
 - Proceso que consiste en variar sistemáticamente la impedancia presentada a un puerto de un dispositivo, destinado a evaluar una performance dada (η, Pout, G, etc.)
 - Se aplica en condiciones de gran señal cuando las aproximaciones lineales (superposición) ya no son aplicables
 - Load Pull manual



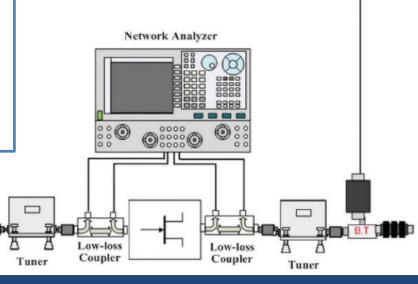


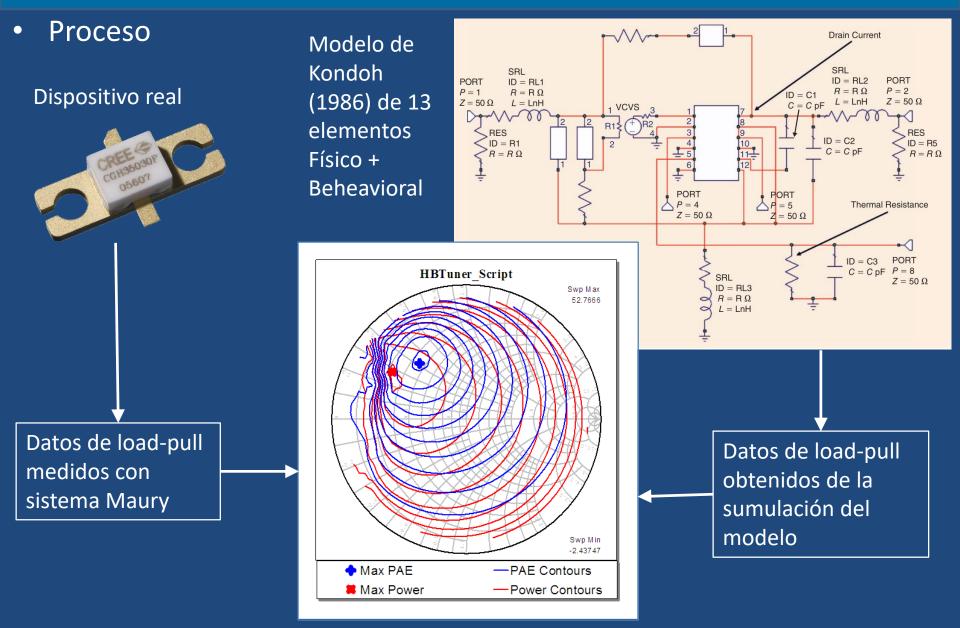
Amplifier

PNA-X Source 1

- Sistema automático con sintonizadores Maury
- Set-up con PNA-X nonlinear vector network analyzer (NVNA), fuente de polarización (oculta atrás), sintonizadores externos Maury y software de captura

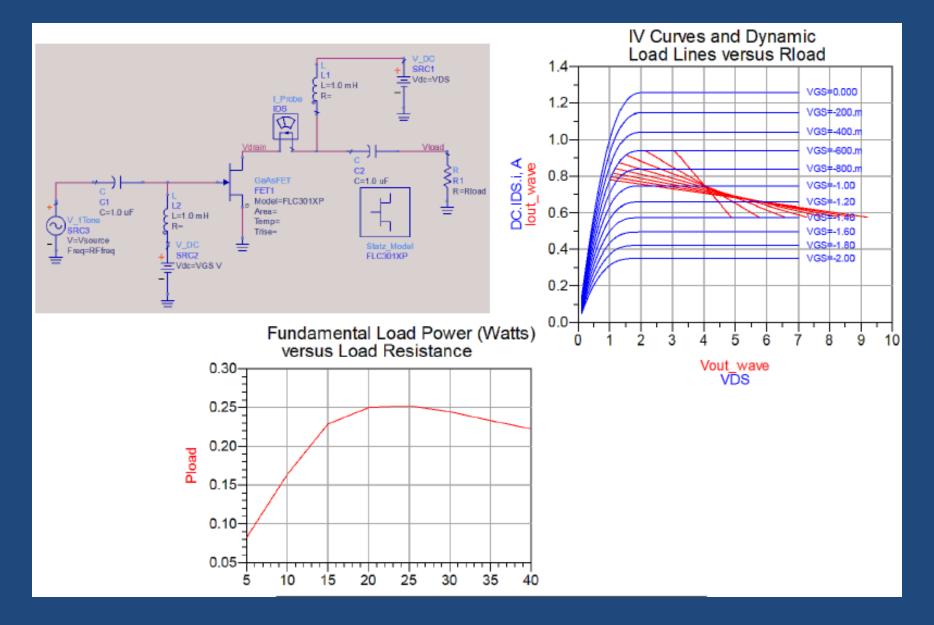
Descripción funcional



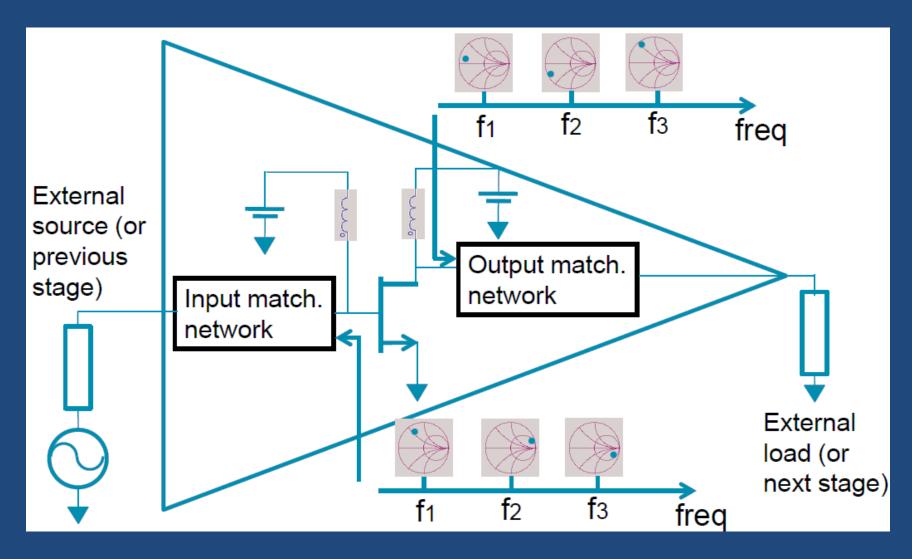


Contornos de load-pull con simulador

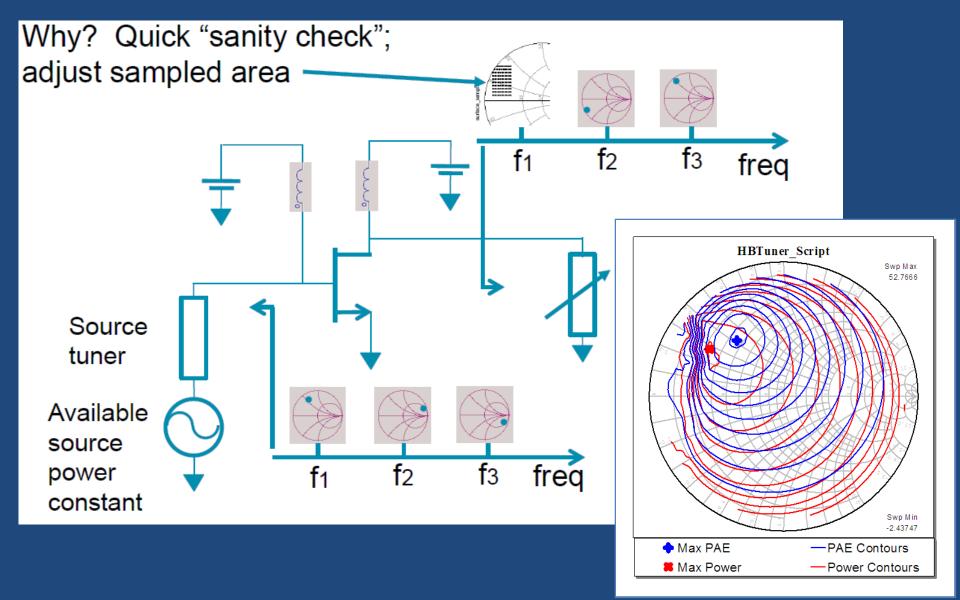
Un caso de load pull extremadamente simple



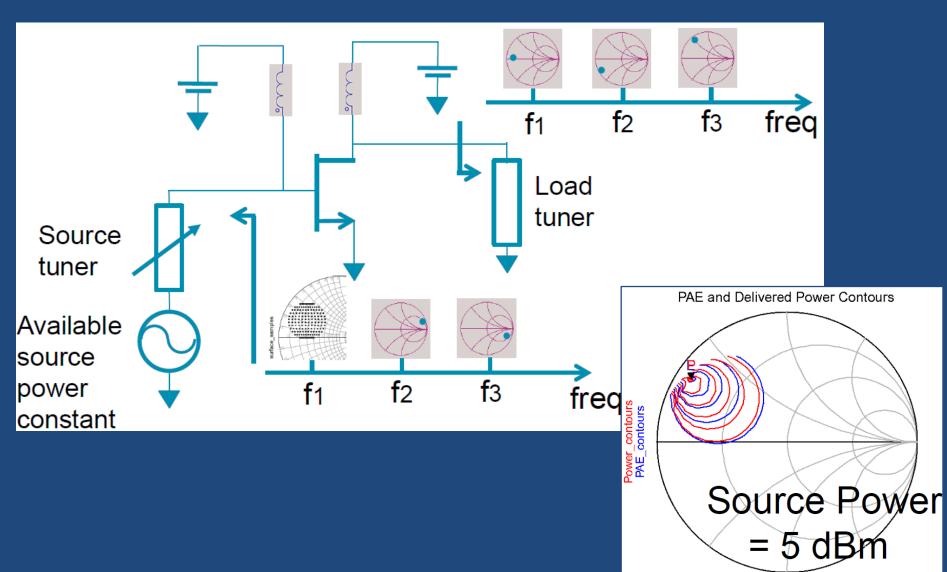
 La performance del dispositivo depende de las impedancias de carga y de fuente para cada armónico



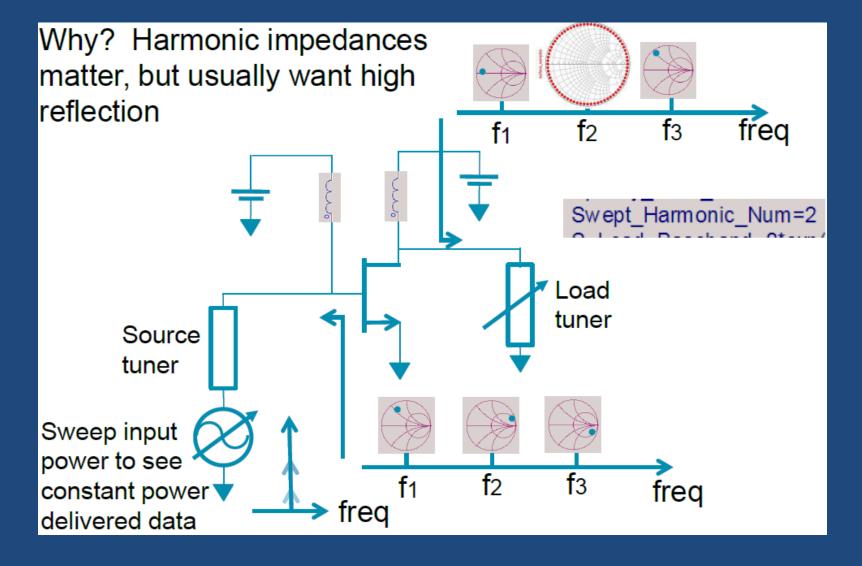
 Se evalúa el comportamiento de un parámetro del circuito variando solo la impedancia de la cual se quiere conocer su influencia sobre un área de la carta



 Normalmente la impedancia de fuente que da mejor rendimiento también provee mejor potencia de salida

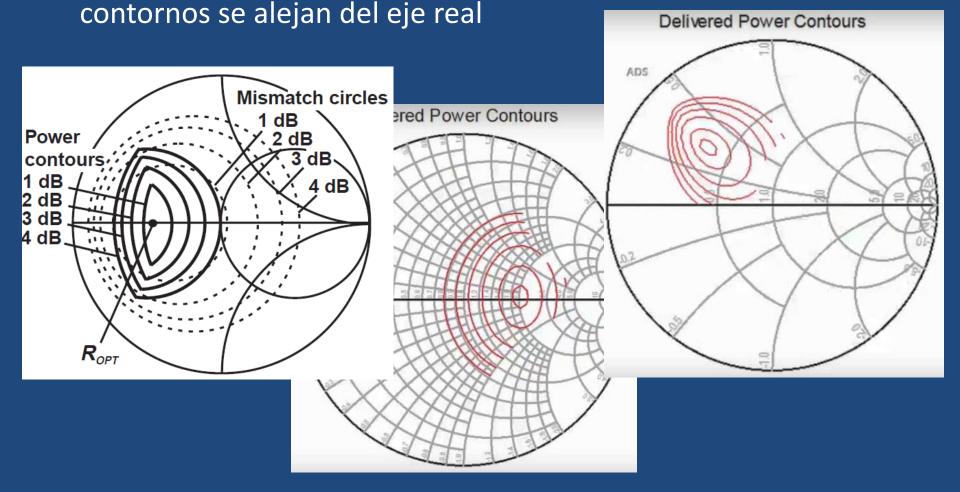


 Sintonizar adecuadamente las impedancias en las f armónicas aumenta el rendimiento

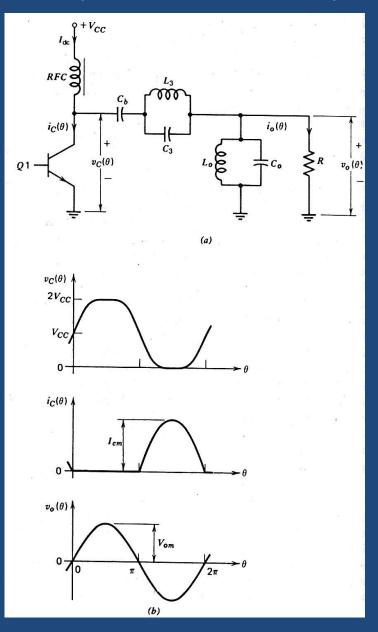


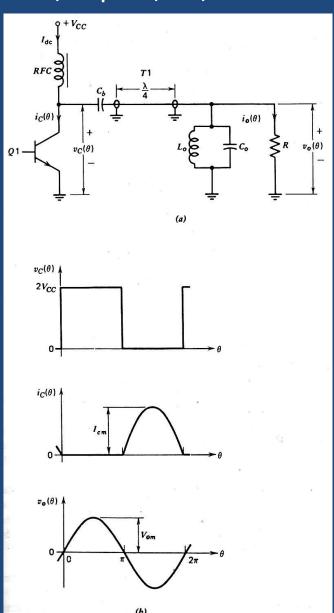
 La teoría predice que los contornos de Pout o PAE constante en baja f siguen la líneas de resistencia o conductancia constante*

En alta frecuencia los parásitos se tornan significativos y los



• Amplificador Clase F: η teórico, izq. 88,4%, derecha 100%





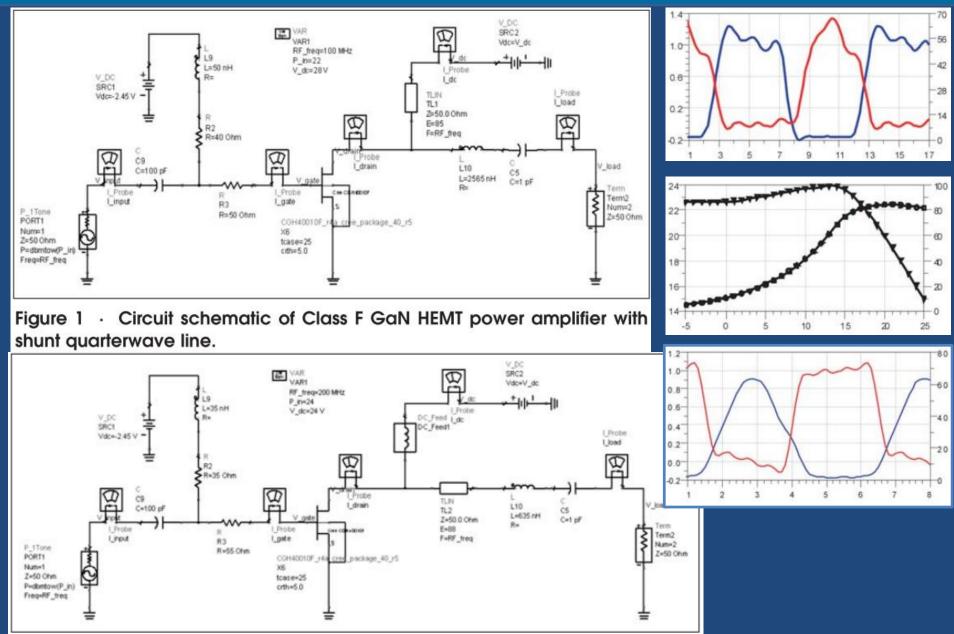


Figure 3 · Circuit schematic of inverse Class F GaN HEMT power amplifier with series quarterwave line.

 La síntesis de redes de adaptación es un problema complejo

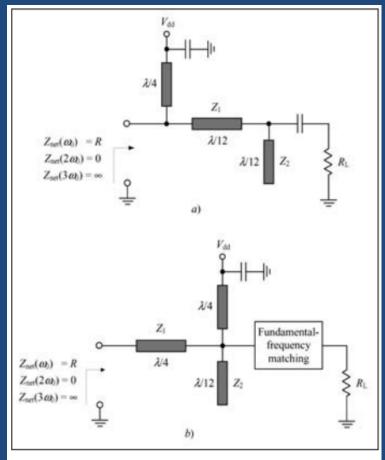


Figure 5 · Idealized transmissionline Class F load networks.

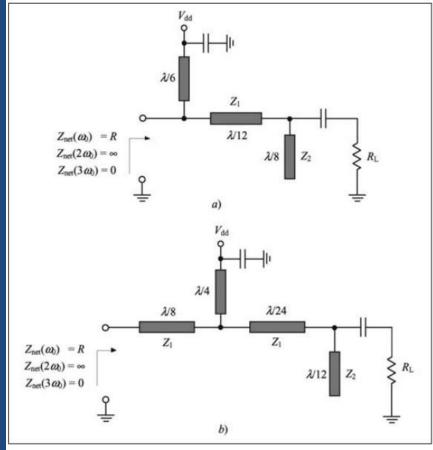
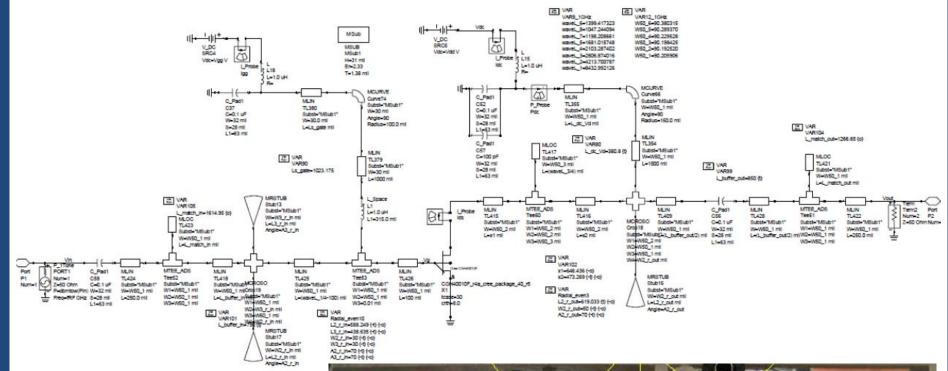
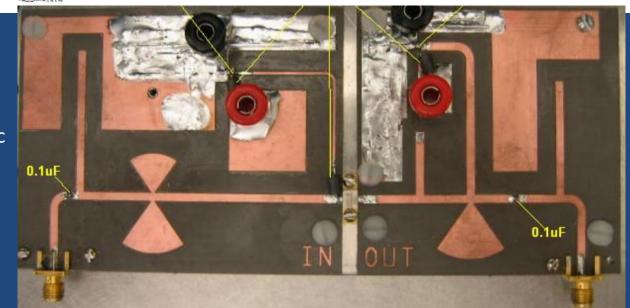


Figure 6 · Idealized transmission-line inverse Class F load network.

* Tomado de Load Network Design Technique for Class F and Inverse Class F Pas By Andrei Grebennikov, Bell Labs, Alcatel-Lucent



*A Master Thesis presented to the Faculty of California Polytechnic State University, San Luis Obispo In Partial Fulfillment of the Requirements for the Degree Master of Science in Electrical Engineering By Kai Shing Tsang August 2010



Dispositivo

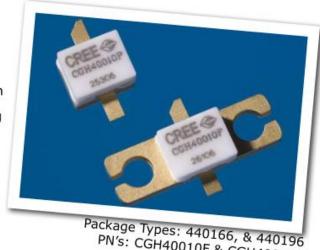
10W=40dBm 13W=41,1dBm

CGH40010

10 W, RF Power GaN HEMT

Cree's CGH40010 is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT). The CGH40010, operating from a 28 volt rail, offers a general purpose, broadband solution to a variety of RF and microwave applications. GaN HEMTs offer high efficiency, high gain and wide bandwidth capabilities making the CGH40010 ideal for linear and compressed amplifier circuits. The transistor is available in both screw-down, flange and solderdown, pill packages.





PN's: CGH40010F & CGH40010P

FEATURES

- Up to 6 GHz Operation
- 16 dB Small Signal Gain at 2.0 GHz
- 14 dB Small Signal Gain at 4.0 GHz
- 13 W typical P_{SAT}
- 65 % Efficiency at P_{SAT}
- 28 V Operation

APPLICATIONS

- 2-Way Private Radio
- **Broadband Amplifiers**
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB, Linear amplifiers suitable for OFDM, W-CDMA, EDGE, CDMA waveforms

Valores máximos



Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V _{DSS}	84	Volts	25°C
Gate-to-Source Voltage	V_{GS}	-10, +2	Volts	25°C
Storage Temperature	T_{stg}	-65, +150	°C	
Operating Junction Temperature	T,	225	°C	
Maximum Forward Gate Current	I_{GMAX}	4.0	mA	25°C
Maximum Drain Current ¹	I_{DMAX}	1.5	Α	25°C
Soldering Temperature ²	T_s	245	°C	
Screw Torque	τ	60	in-oz	
Thermal Resistance, Junction to Case ³	$R_{_{\theta JC}}$	8.0	°C/W	85°C
Case Operating Temperature ^{3,4}	T _c	-40, +150	°C	

Note:

¹ Current limit for long term, reliable operation